

Electronic Patent Application Fee Transmittal

Application Number:	10623679			
Filing Date:	22-Jul-2003			
Title of Invention:	RESIST PATTERN THICKENING MATERIAL, RESIST PATTERN AND PROCESS FOR FORMING THE SAME, AND SEMICONDUCTOR DEVICE AND PROCESS FOR MANUFACTURING THE SAME			
First Named Inventor/Applicant Name:	Koji Nozaki			
Filer:	LEE C WRIGHT/Akemi Ferebee			
Attorney Docket Number:	030891			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	2	3	6
Total in USD (\$)				1816